

EE 213, Microscopic Nanocharacterization of Materials

Lecture 7. *Xray Microanalysis (cont.)*

Class website: <https://ee213-winter16-01.courses.soe.ucsc.edu>

Mike Isaacson, Baskin 237

Email: msi@soe.ucsc.edu

Tele: 831-459-3190

Admin. Asst. Rachel Cordero: rcordero@soe.ucsc.edu, 831-459-2921

EE213 Paper Notes

- See IEEE.jour for formatting notes. On class web site.
- Paper should be about 10 pages long including figures.
- Paper should include a 1 paragraph abstract
- Paper should have at least 10 references.
- For each reference, either a summary or the abstract of that reference attached as an Appendix to the paper.

EE213. W16

Homework 1

Due: 2.11.16

Max Score = 100

Note: if you take data from the literature, you need to reference the article.

1. (50 pts.) Consider a 150nm thick garnet sample irradiated by a focused 10nm diameter electron beam of 100KeV energy. The electron beam is normal to the sample surface and the point where the beam strikes the garnet is 20mm from the front of the detector which is the same Si(Li) XRay detector as in problem2. The detector axis is 45 degrees to the sample surface. From the table below, calculate the relative mass fraction ratios of the elements indicated. The counts represent the integrated counts under the Ka XRay peak after subtracting off the bremsstrahlung XRay background. Note: you need to decide if you are able to use the thin film approximation.

Element	counts
Mg	7600
Al	9,100
Si	20.600
Ca	4,400
Ti	900
Cr	1,200
Fe	8,100

2. (50 pts) A manufacturer of a Si(Li) XRay detector claims that the detector is more than 90% efficient at detecting any $K\alpha$ XRay from Na to Nd. The specification of the detector is shown below:

3mm thick active region
10 micron thick Be vacuum window
35 nm thick Au front contact layer (ie, facing the XRays)
300nm thick Si dead layer on the front surface
20 square mm active area

A) (25 pts) Are the claims true? Explain.

B) (25 pts) Could this detector be used to detect oxygen $K\alpha$ Xrays? Explain.

[NIST Home](#) > [PML](#) > [Physical Reference Data](#) > [Stopping-Power & Range Tables: e-, p+, Helium Ions](#)

[NISTIR 4999](#) | [Version History](#) | [Disclaimer](#)

Stopping-Power and Range Tables for Electrons, Protons, and Helium Ions

M.J. Berger, J.S. Coursey, M.A. Zucker and J. Chang
(NIST, Physical Measurement Laboratory)



Abstract:

The databases ESTAR, PSTAR, and ASTAR calculate stopping-power and range tables for electrons, protons, or helium ions, according to methods described in ICRU Reports 37 and 49. Stopping-power and range tables can be calculated for electrons in any user-specified material and for protons and helium ions in 74 materials.

Contents:

- [1. Introduction](#)
- [2. ESTAR: Stopping Powers and Ranges for Electrons](#)
- [3. PSTAR and ASTAR: for Protons and Helium Ions \(alpha particles\)](#)

[References](#)

[Appendix: Significance of Calculated Quantities](#)

Access the Data:

Select Language

SHARE [f](#) [t](#) [e](#) ...

Powered by [Google Translate](#)



© Creations/2010 Shutterstock.com

Access the Data

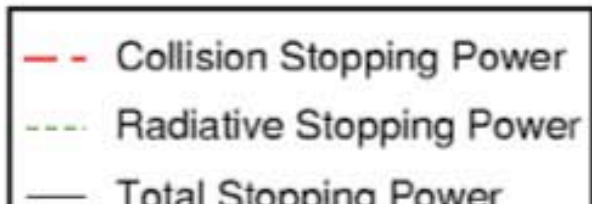
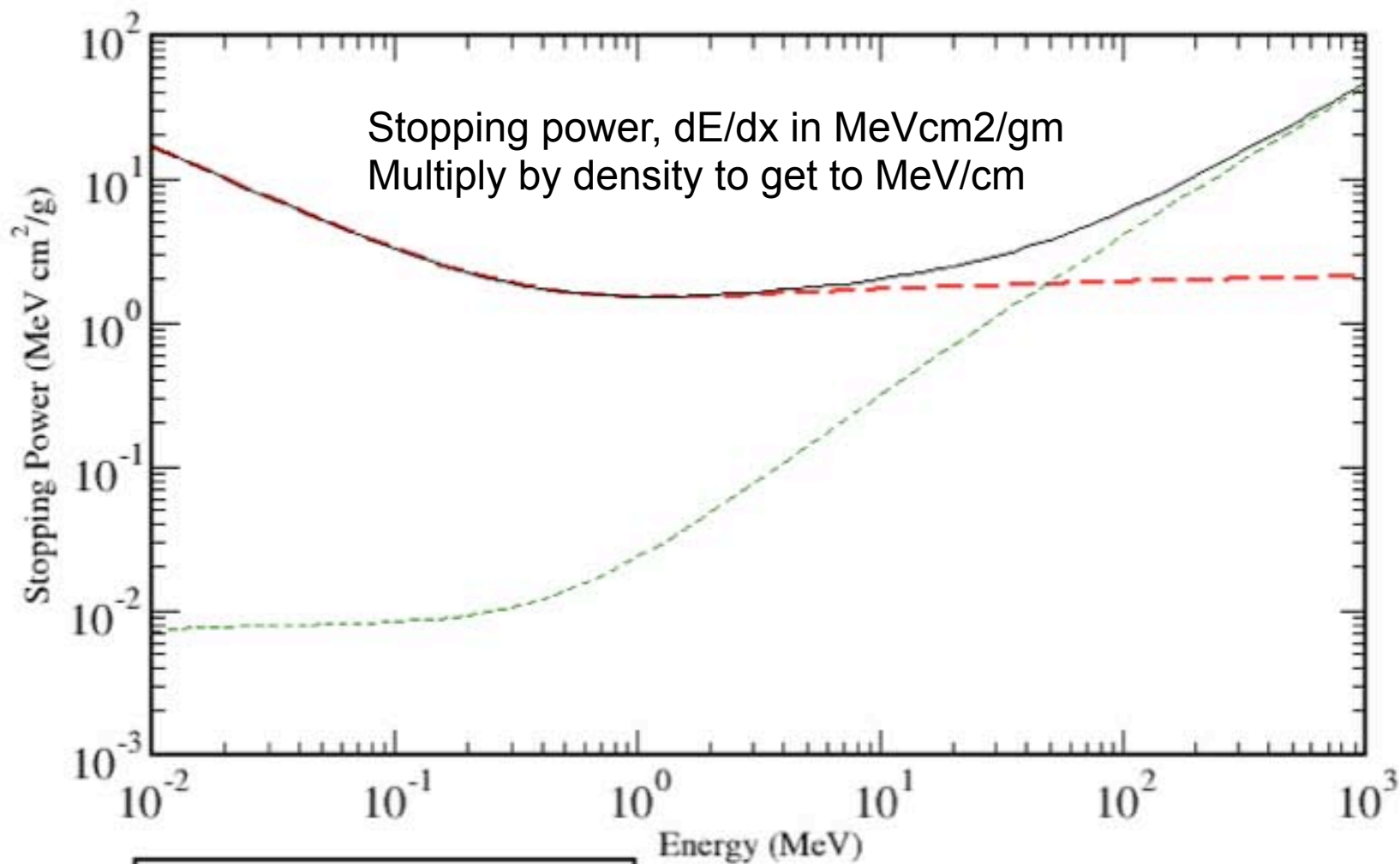
[Electrons](#) | [Protons](#) | [Helium Ions](#)

NIST Standard Reference Database 124

Rate our products and services.

Online: October 1998 - **Last update:** August 2005

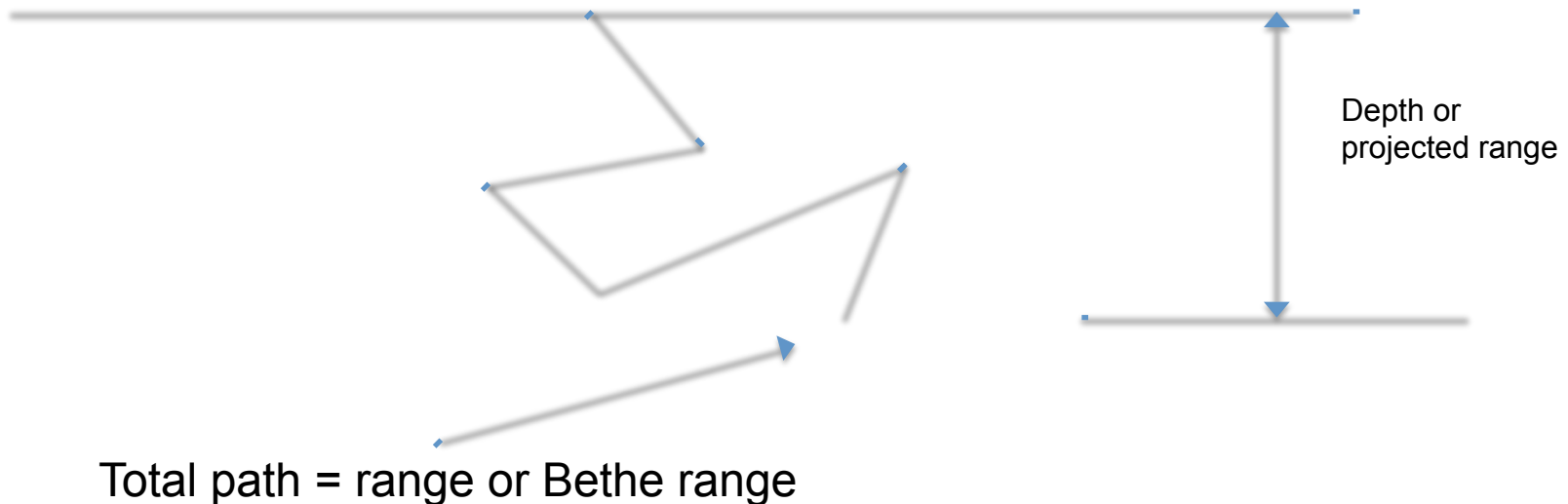
SILICON

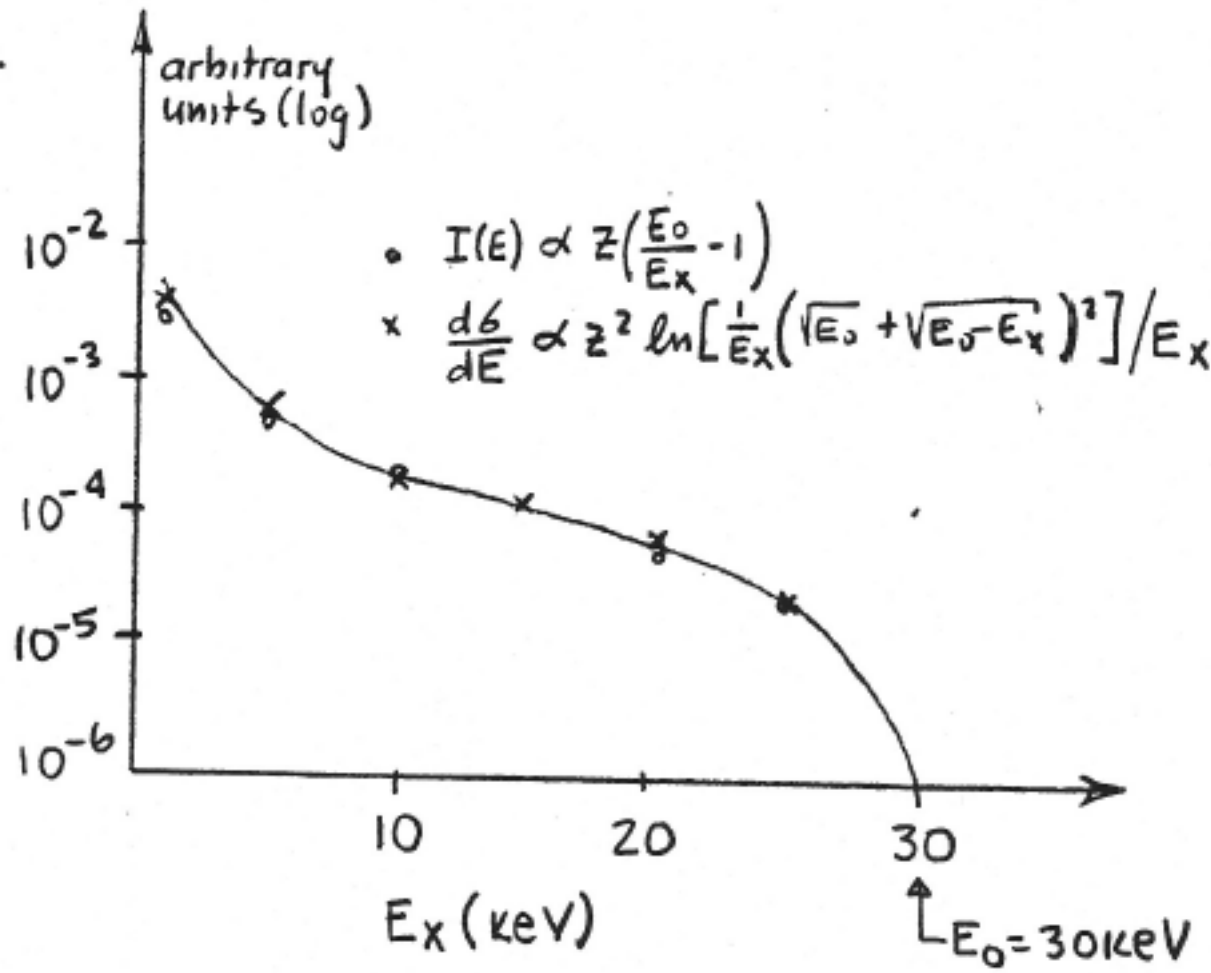


We are usually interested in region less than 1 MeV

Stopping power and range

- Note that $dE/dx = \langle E \rangle_{\text{avg}} / \Lambda_{\text{in}}$ approx.
- $\langle E \rangle_{\text{avg}} = 13.5Z^{1/2} \text{ eV}$



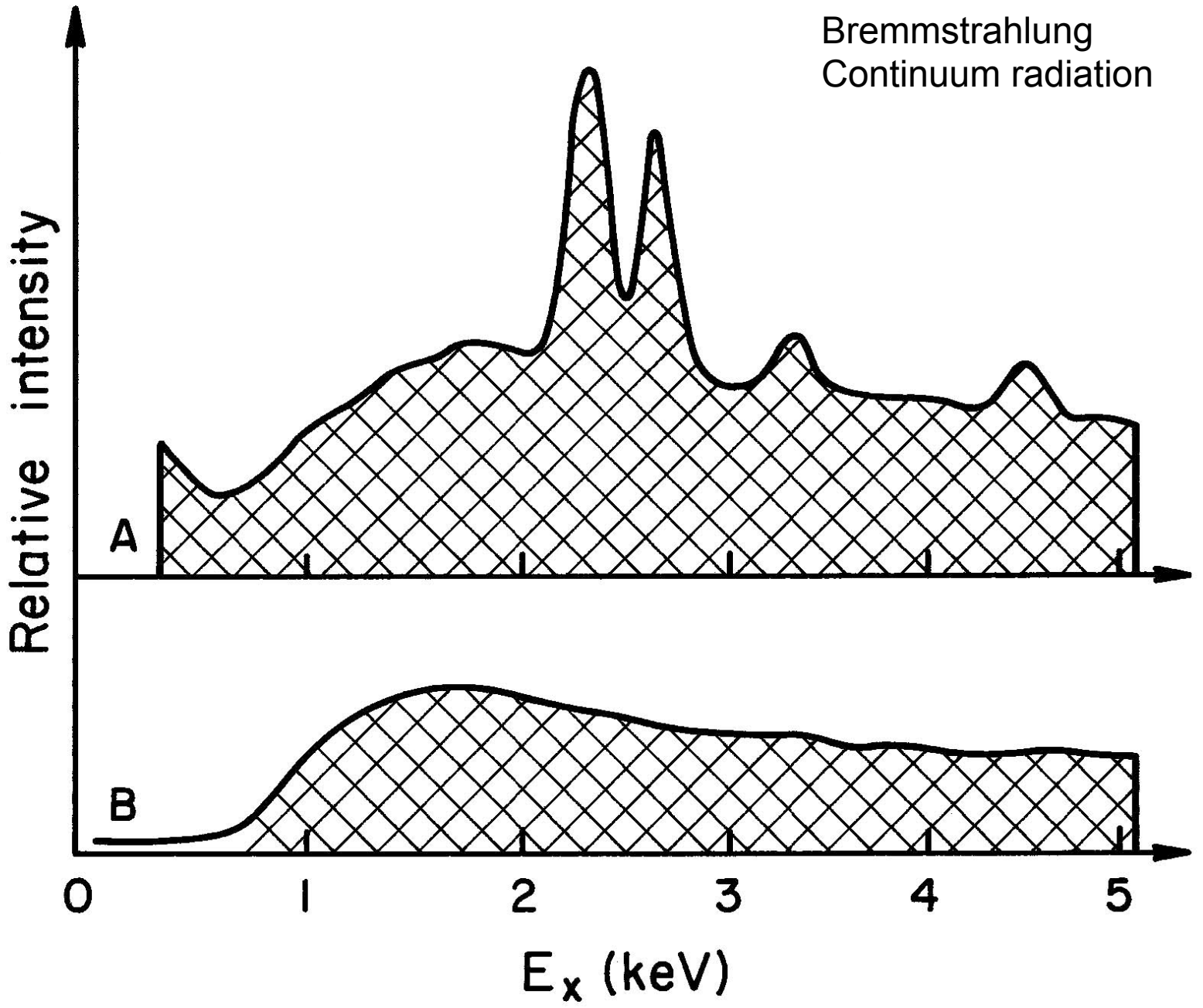


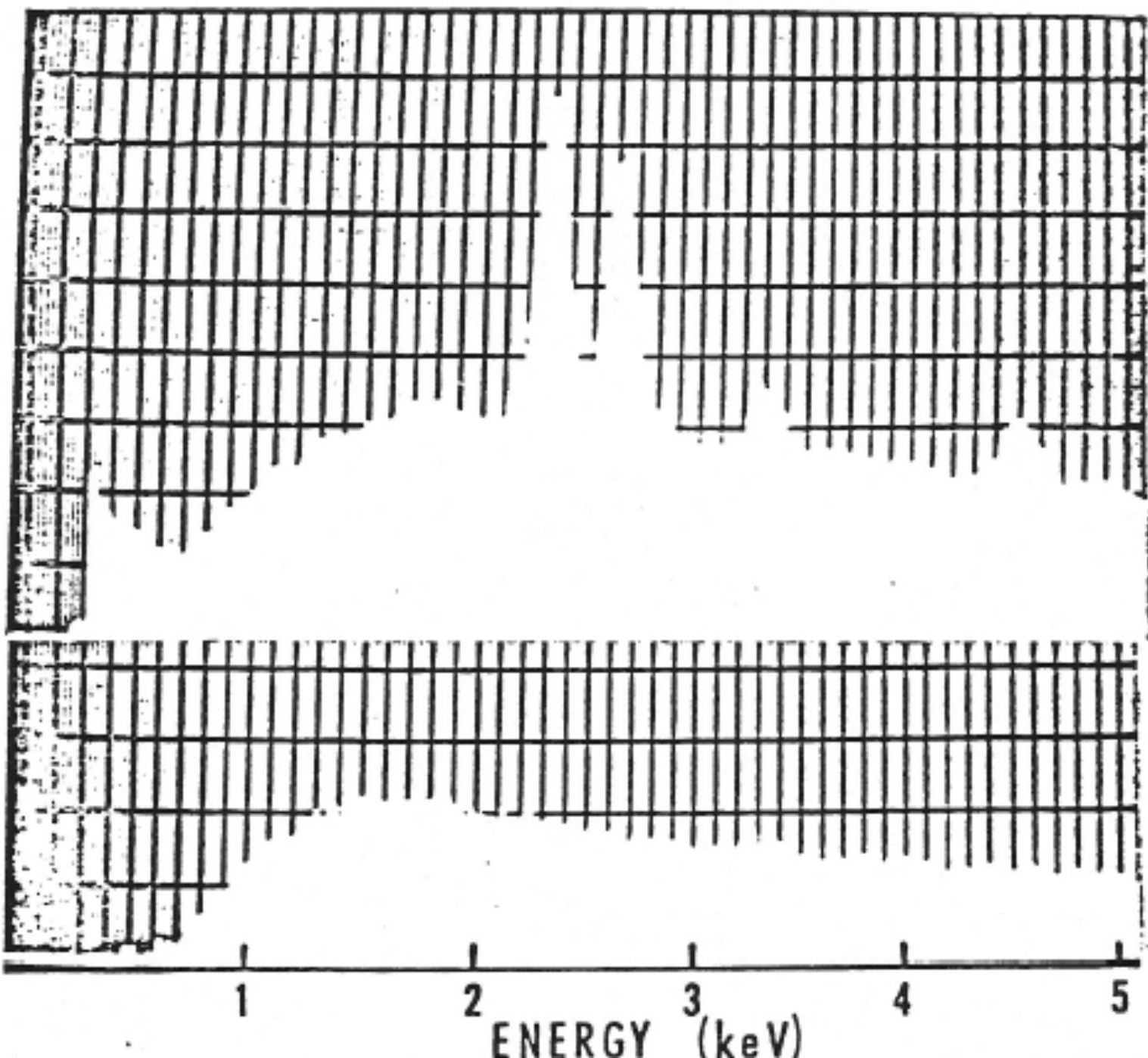
results normalized at 15 keV

$I(E) \rightarrow$ solid target emission (Kramers, 1923)

$\frac{d\delta}{dE} \rightarrow$ semi-classical electron slowing down (Jackson, 1962)

— Figure 2. —





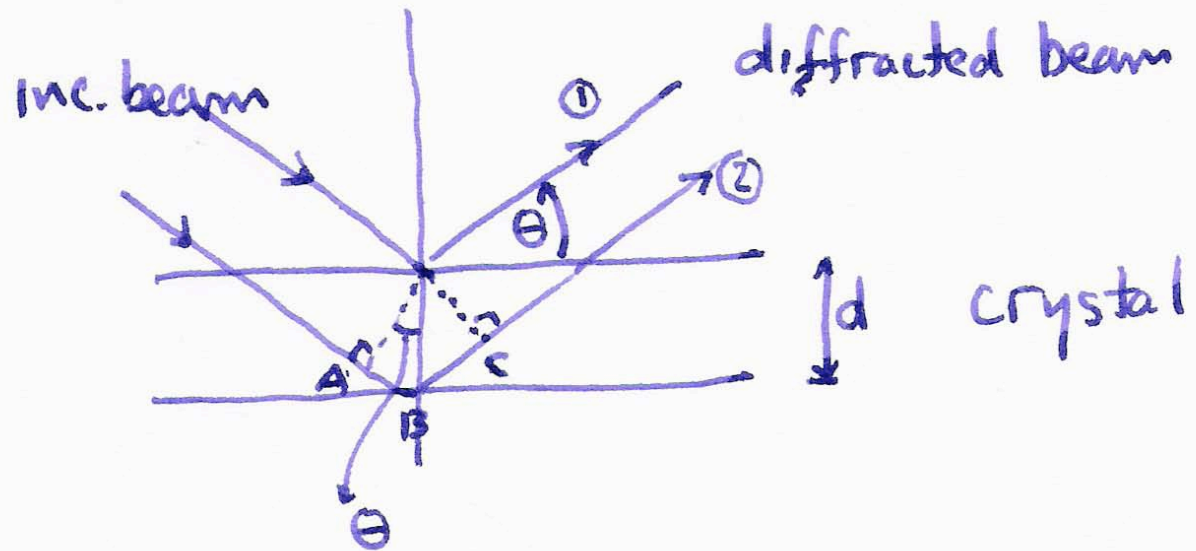
raw spectra
of biological
section 100
thick take
with Si(Li)
detector at
100 keV elec

— low energy
is due to d
transmissio
function

Bremstrahlung
spectrum af
subtraction of
characteristic
and. extraneous
background

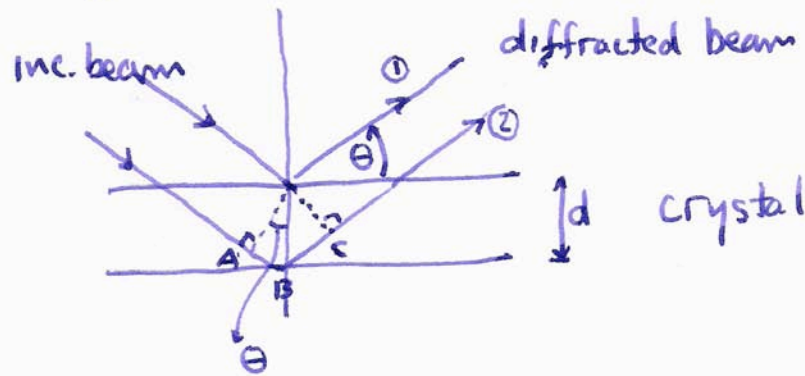
How to Detect X Rays?

1. by wavelength (WDS)



How to Detect X Rays?

1. by wavelength (WDS)



path difference between ① and ② is:

$$\overline{AB} + \overline{BC} = 2d \sin \theta$$

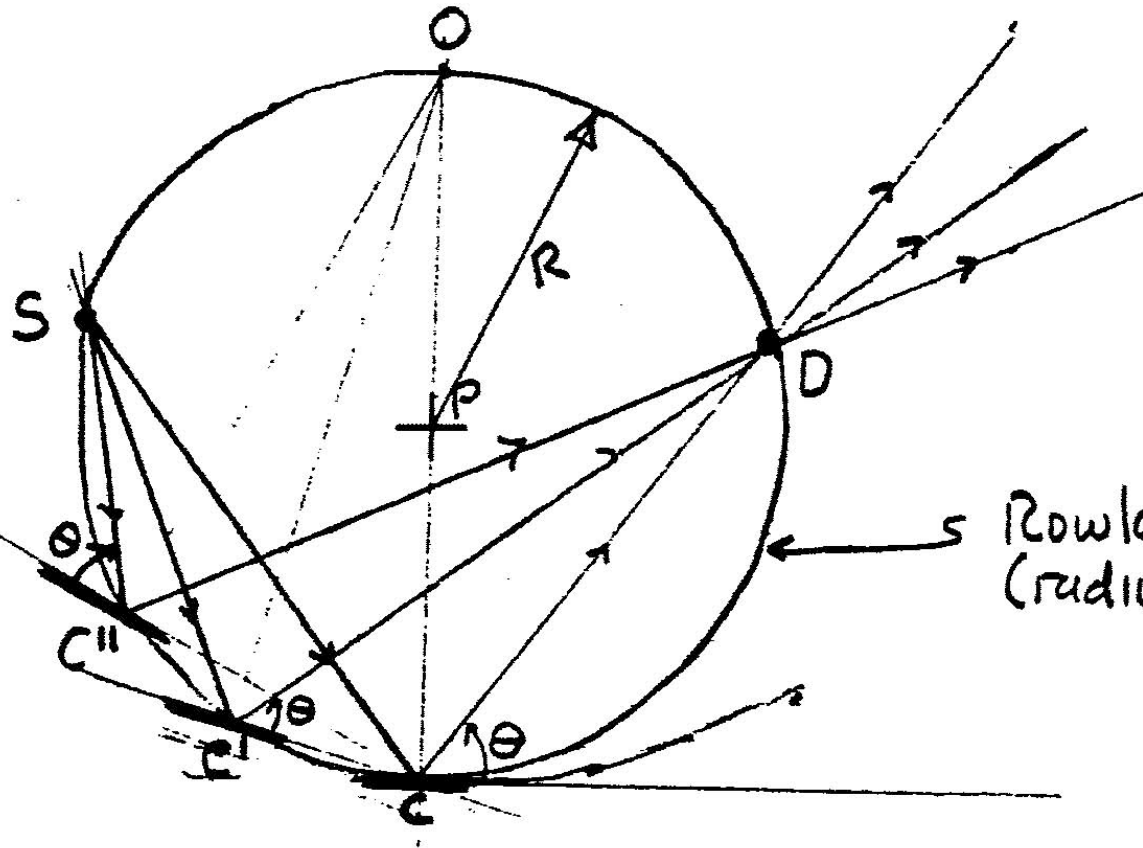
constructive interference between the two beams diffracted (reflected) off the 2 layers is:

$$\text{path diff} = n \lambda \quad , n=0,1,2.$$

$\lambda = \text{X-ray wavelength}$

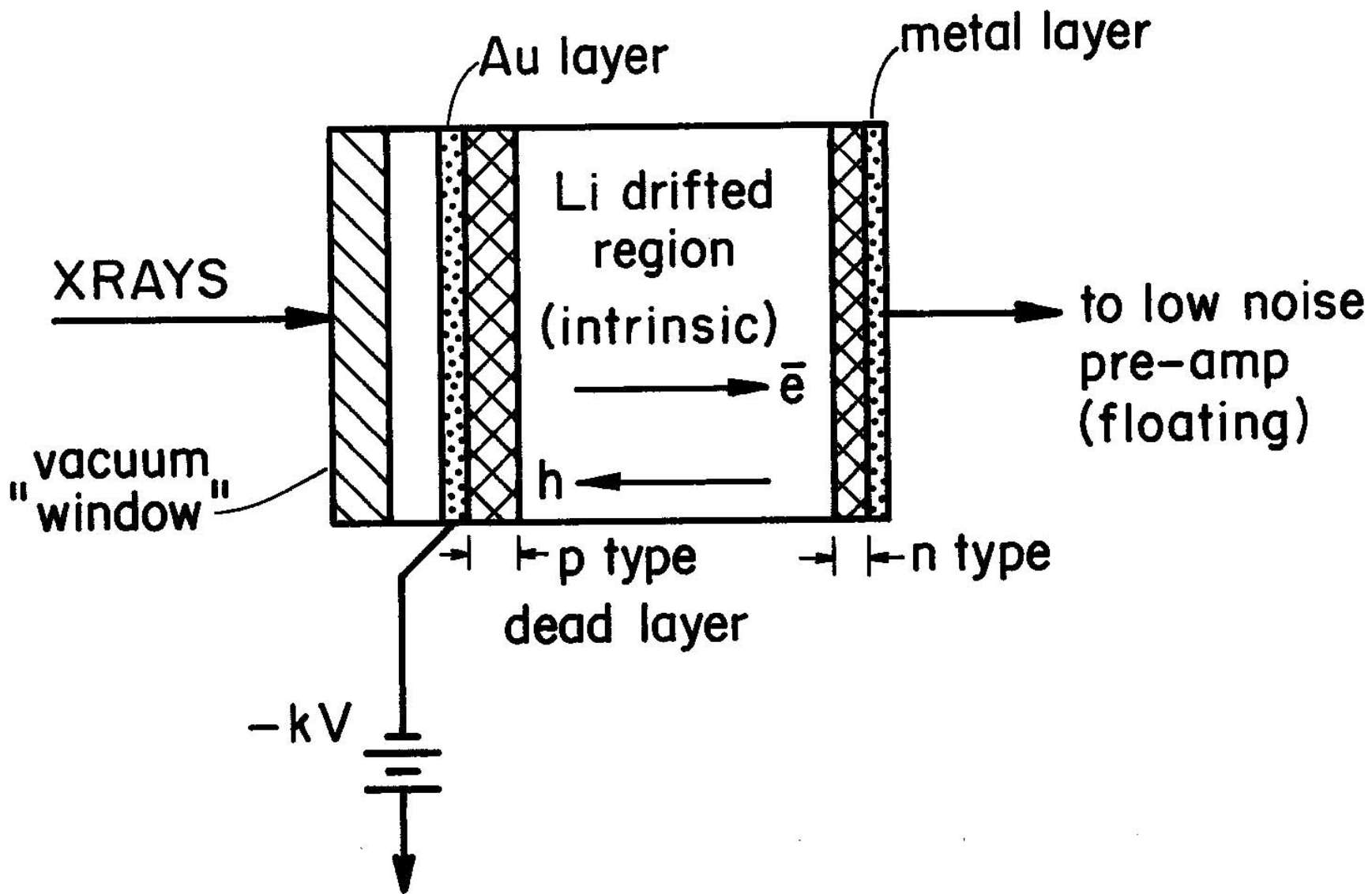
$$\therefore \boxed{n \lambda = 2d \sin \theta} \quad \text{Bragg's law} \rightarrow E = h\nu = \frac{hc}{\lambda}$$

crystal spectrometer geometry



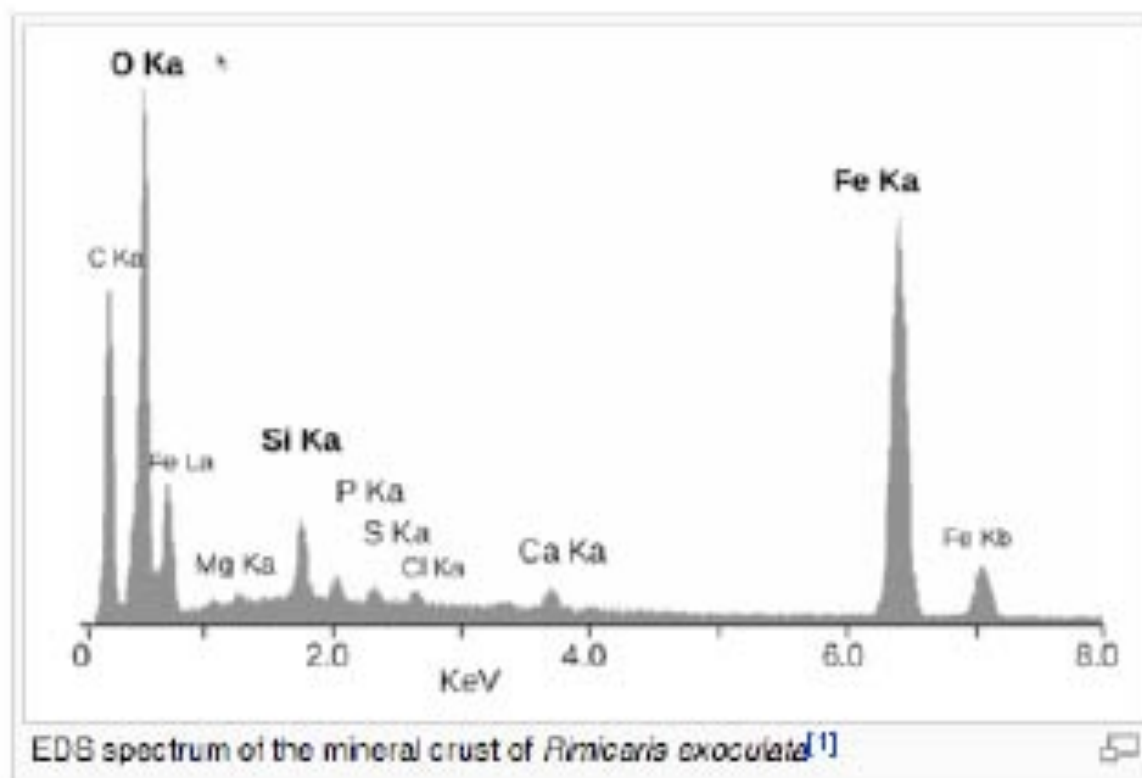
$$\overline{OP} = R = \overline{PC}$$

Rowland Circle
(radius = R)



Energy Dispersive XRay Analysis (real detector/sample)

From: L.Corbari, et.al. Biogeosciences.5.(2008).1295-1310.



Comparison between EDS and WDS
 X-Ray Spectra from the same material
 (from NBS.)

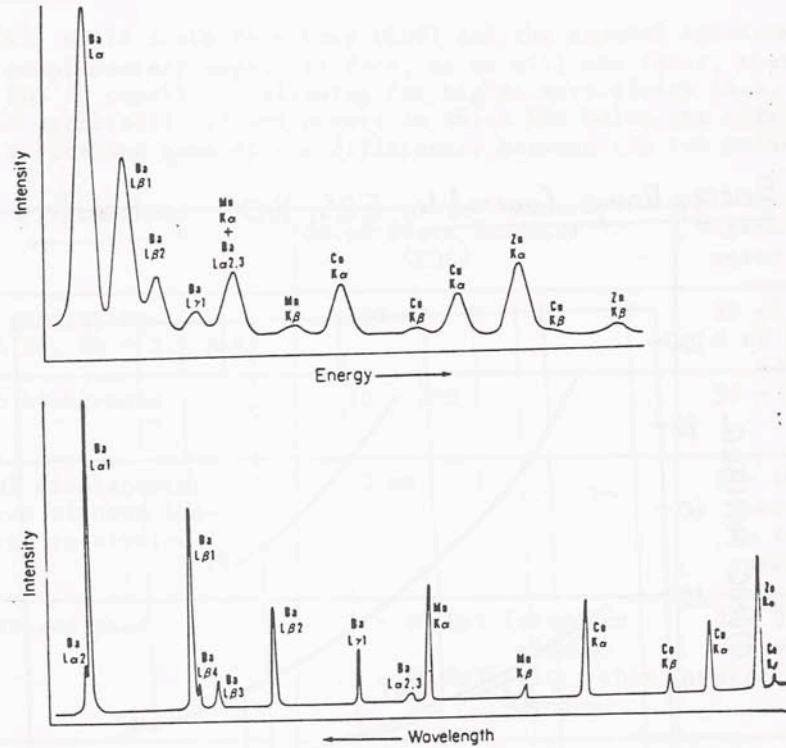
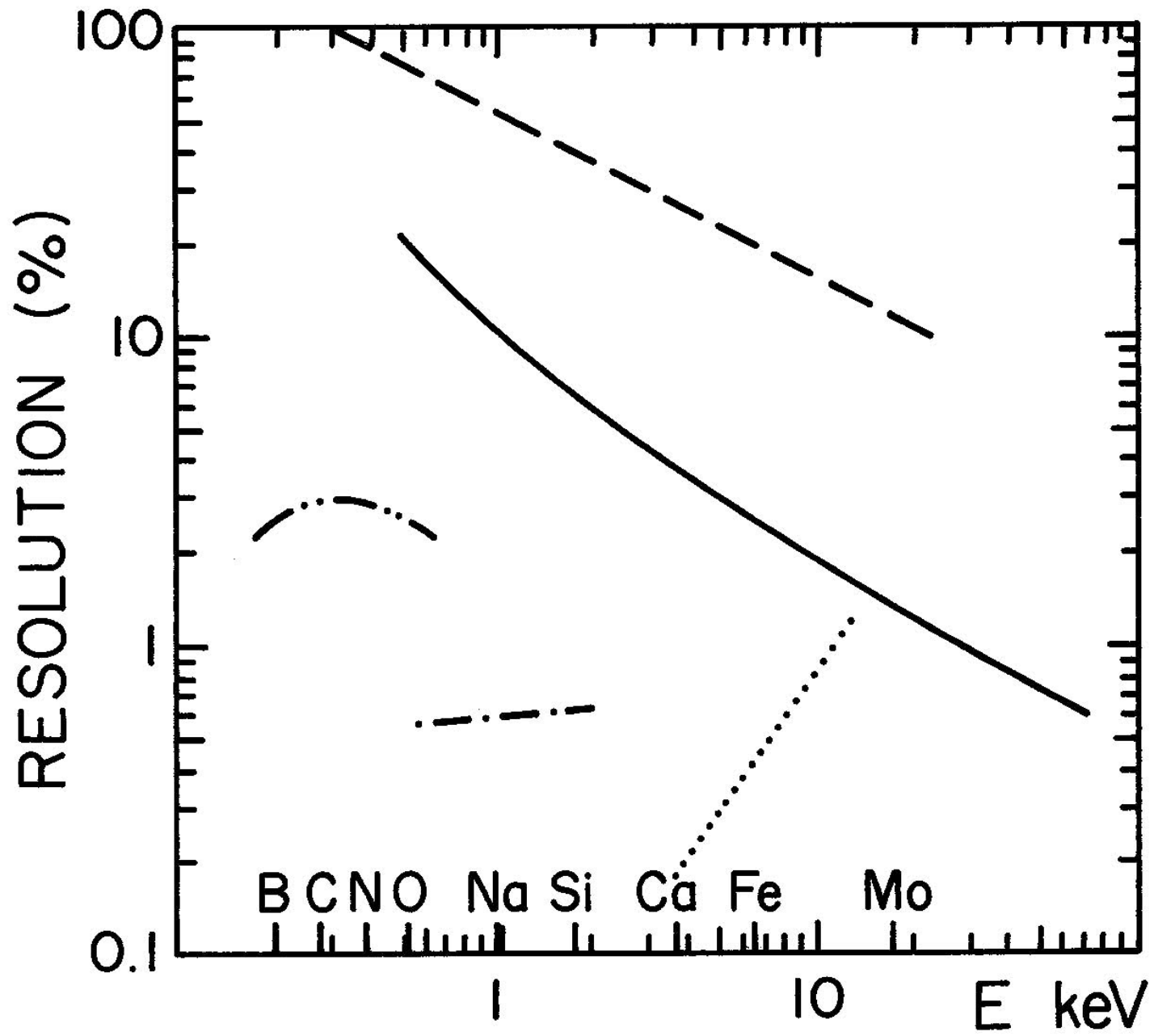
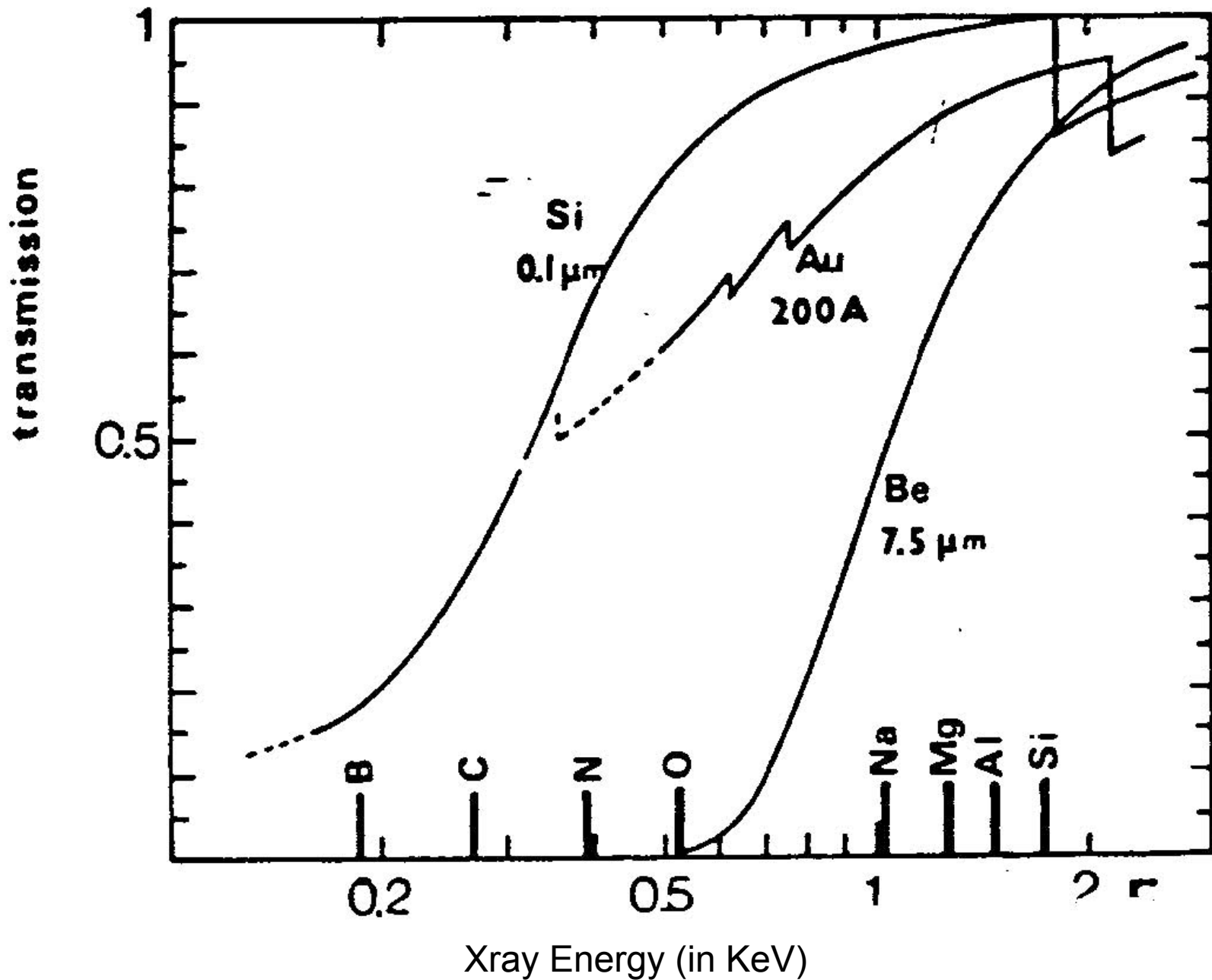


Fig. 5.24. Comparison of spectra of a glass (NBS K252) with a Si(Li) detector (above) and with a 10-cm radius LiF curved-crystal spectrometer (below). Both performed at 20-kV excitation potential. The composition of the glass is as follows: SiO₂: 0.40, BaO: 0.35, MnO: 0.10, MnO₂: 0.05, CuO: 0.05, CoO: 0.05, all mass fractions.

NOTE energy resolution, range and peak to background differences





X-Ray Analysis (cont)

(12)
(21)

2. Li Drifted Si, energy dispersive

Li acts as donor to compensate for impurity acceptor levels (B)

- results in intrinsic region in which e^-h^+ can only be created by external ionizing radiation.
- bias the detector to drag e^- to 1 side.

X-ray absorbed in intrinsic layer, E_x

$$\#e^-h^+ \text{ pairs produced} = \frac{E_x}{E} \rightarrow 3.7 \text{ eV in Si}$$

$$\therefore \text{charge collected } Q = \left(\frac{E_x}{E}\right) \cdot e$$

detector has capacitance, so we actually get

$$\text{a voltage pulse } V = \frac{Q}{C} = \frac{e}{C} \left(\frac{E_x}{E}\right)$$

pulse ht \propto X-ray energy \rightarrow energy dispersive
we count pulses (one at a time)

assuming Poisson statistics for Q then

$$\text{stand. dev. of voltage pulse is } \Delta V = \frac{e}{C} \sqrt{\frac{E_x}{E}}$$



not Poisson
exactly
 $\Delta N < \sqrt{N}$

$$\therefore \frac{\Delta V}{V} = \frac{\frac{e}{C} \sqrt{\frac{E_x}{E}}}{\frac{e}{C} \left(\frac{E_x}{E}\right)} = \sqrt{\frac{E}{E_x}} \quad \left(\frac{\sqrt{N}}{N}\right)$$

$$\therefore \frac{\Delta E_x}{E_x} = \sqrt{\frac{E}{E_x}} \Rightarrow \Delta E_x = \sqrt{E E_x}$$

energy res.

for a Gaussian distrib: FWHM = 2.36 ΔE_x

X-Ray Aral (cont)

(23)

call $\frac{\text{St. dev}}{N} = F \Rightarrow$ for Poisson, $F=1$

$F = \text{Fano factor} - \text{for Si(Li)} = .12 \leftarrow$

$$\therefore \boxed{\Delta E_x^{\text{Si(Li)}} = 1.6 \sqrt{E_x} \text{ in eV}} \leftarrow$$

\leftarrow intrinsic energy resolution

but pulses are small, need amplification

\therefore extra elec. noise

$$\Delta E_{\text{FWHM}} = \sqrt{(1.6 \sqrt{E_x})^2 + E_{\text{elec noise}}^2}$$

$\leftarrow E_{\text{elec}} \sim 50-100 \text{ eV} //$

$//$ need to cool to 4K N_2
 $//$ to reduce thermal noise

efficiency of detector:

1) solid \angle

2) window, metalization, layer, dead layer etc ..

\leftarrow all of these depend upon the X-ray energy

2 effects:

1) x-ray absorption in these layers
resulting in fewer e^-h^+ produced

2) x-rays of high enough energy
and get absorbed in the intrinsic layer

this is similar for all EDX type detectors —

X-Ray Analysis (cont)

(24)

185

consider the effluence resulting from these various layers

$$f_{\text{DET}} = \left[\prod_i e^{-\left(\frac{\mu}{\rho}\right)_i (\rho t)_i} \right] \left[1 - e^{-\left(\frac{\mu}{\rho}\right)_A (\rho t)_A} \right]$$

product of absorption in each layer

probability that A x-ray won't be absorbed in intrinsic region

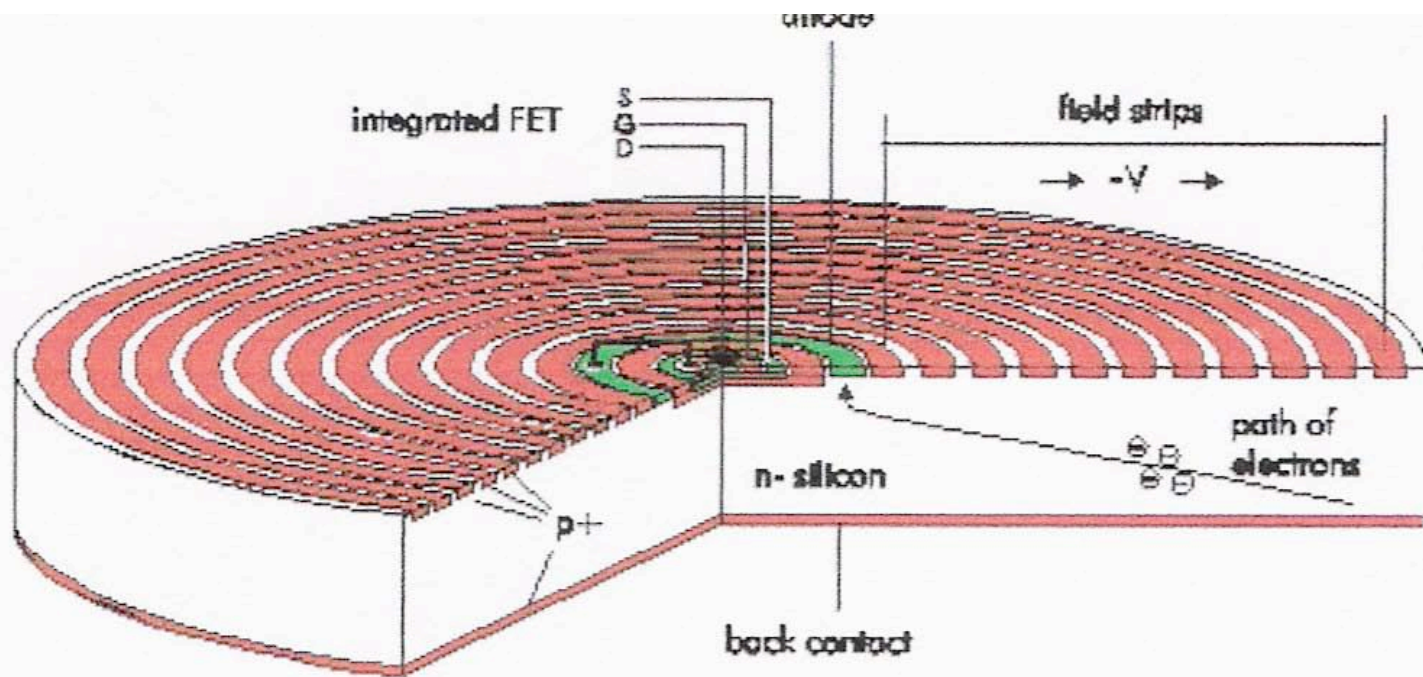
NOTE: if we calc for a layer of given thickness t , we can do any thickness t' as $t' = Nt \implies e^{-Nt} = (e^{-t})^N$ ///

it is clear that to minimize absorption in front layers, want to make them as thin as possible.

best is "windowless" detector - no vacuum window barriers // probs.

we can trans. char of diff. det. materials

pt. to note /- light element detection is poor since x-ray energies are so low - any kind of physical window cuts down on transmission.



Silicon Drift Detector for X-ray spectroscopy.

[up]

3. silicon drift detector (SDD).

same Si PN junction concept. (1983)

- recently used in EM's for Xray detectors (last few yrs)
differences with Si(Li).

- electric field parallel to the surface (rather than \perp)
- drives electrons towards small central anode (thus, lower capac.)

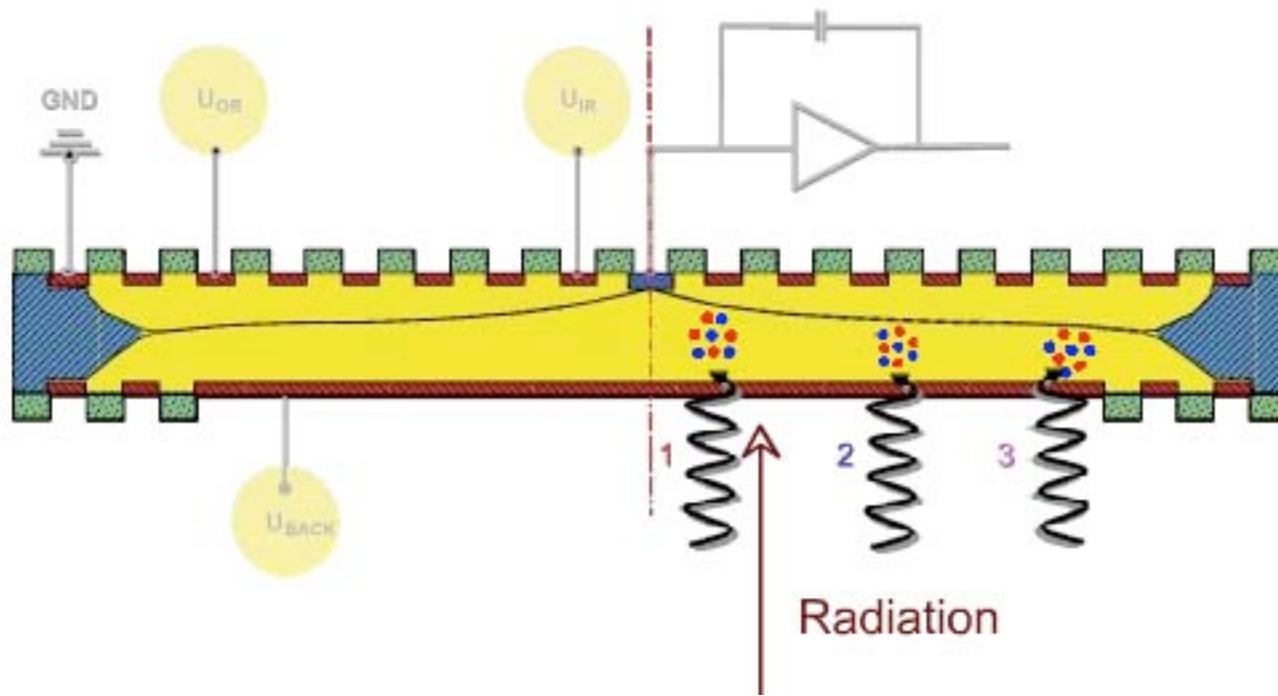
↳ + capac. indep. of active area

whereas in Si(Li) depends on active area.

small capac. means shorter shaping time \rightarrow fast cts rate

- geometry minimizes pickup (elec or mech)
- virtually no det dead time
- leakage current extremely low so no liq N₂ cooling
 - uses Peltier cooling (-20°C vs -170°C Si(Li))
- resolution comparable to Si(Li)

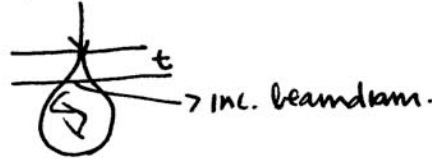
Function of Silicon Drift Detector



X Ray anal (cont)

(14)

spatial resolution of X ray signal for thin films: beam spreading



rough calculation:
considers Rutherford Scatt

$$\begin{aligned} \text{X section } > \theta: \sigma_R(>\theta) &= \int_{\theta}^{\pi} \frac{d\sigma_R}{d\Omega} d\Omega \\ &= \int_{\theta}^{\pi} 2\pi \sin\theta d\theta \left[\frac{z^2}{64\pi^2 a_0^2} \right] \left[\frac{\lambda}{\sin \frac{\theta}{2}} \right]^4 \text{ eV} \\ \text{\AA} \leftarrow \lambda &= \sqrt{150/E_0^*}, E_0^* = E_0 \left[1 + \frac{1}{2} \frac{E_0}{mc^2} \right] \\ &\quad \text{rel. corr. wavelength} \end{aligned}$$

$$\therefore \sigma_R(>\theta) \approx \frac{16z^2}{E_0^{*2}} \text{ctn}^2\left(\frac{\theta}{2}\right) \text{ in } \text{\AA}^2 \text{ of } E_0^* \text{ in eV}$$

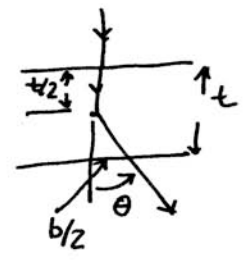
assuming single scatt, then prob. of scatt thru $>\theta$ in dist. t :

$$P(>\theta) = n \sigma_R(>\theta) t.$$

$$\therefore P(>\theta) \propto \frac{ntz^2}{E_0^{*2}} \text{ctn}^2\left(\frac{\theta}{2}\right)$$

X-Ray small (unit)

what is scats α
 whereby 90% events inside?



ie only 10% scattered outside.
 call this $P(> \theta_{0.1}) = 10^{-1}$

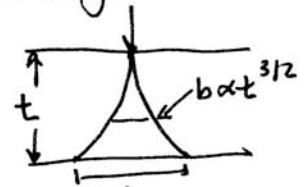
assume (in avg) scats occurs ~~from~~ from middle of film, ~~at~~ at $t/2$ ($< 20^\circ$)

then $\frac{b/2}{t/2} = \tan(\theta_{0.1})$ which for small θ gives:

$$b \propto \frac{1}{E_0} \frac{Z}{A} t^{3/2} \sqrt{P}$$

P in gm/cm^3
 t in cm
 A in gm/mole
 E_0 in eV

that is
 beam spreading $\propto t^{3/2}$



do exam/
 show
 exp means/
 plots

valid in limit $\tan \frac{\theta}{2} \cong \frac{\theta}{2}$ / can find out what that is.

$$t \lesssim 0.312 \times \frac{A}{Z^2 P} E_0^{\#2} \text{ in cm, of } E_0 \text{ ev, } P \text{ in } \text{gm/cm}^3$$

verified by MC calcs

important
 for characterization
 across interfaces

NOTE / for high Z - long tails outside 10% can be significant

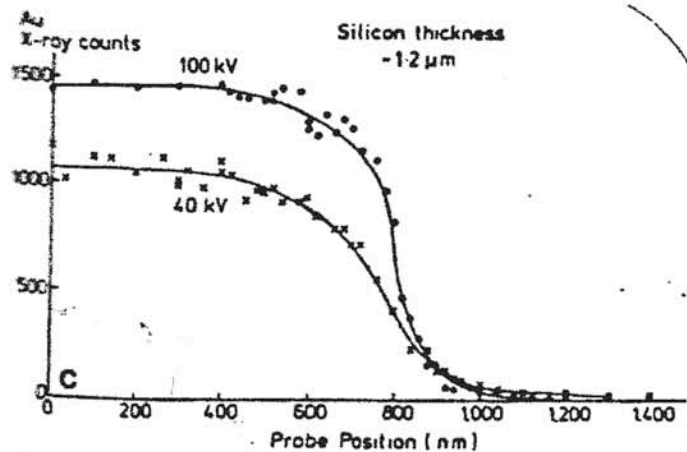
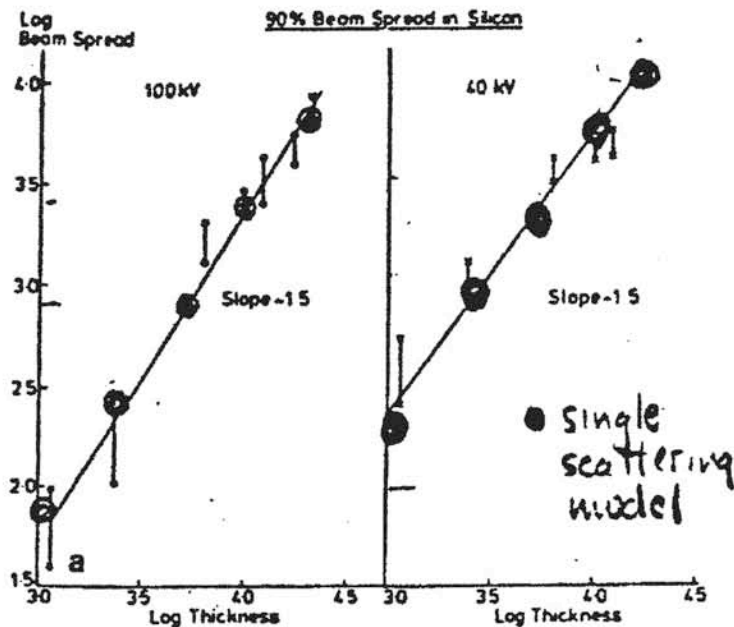
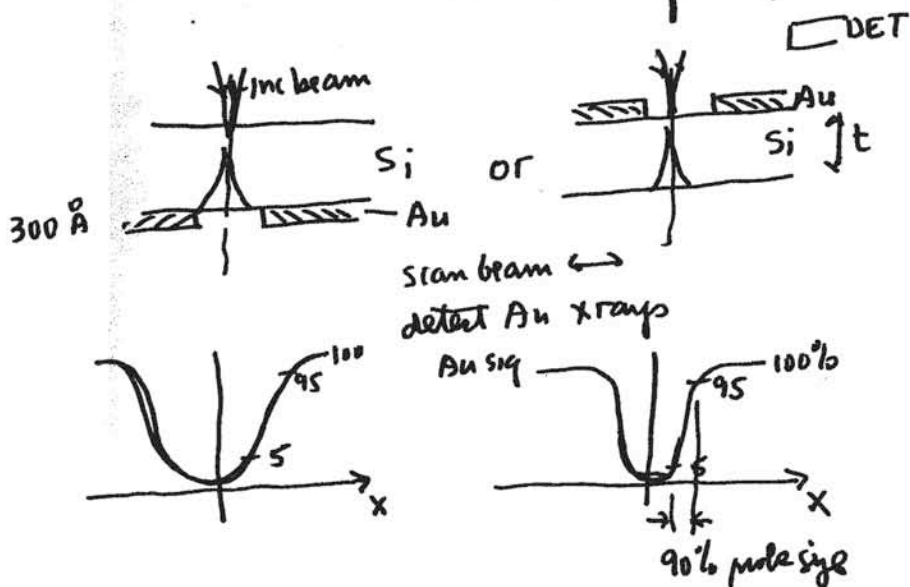


Fig. 3. Au X-ray counts at accelerating voltages of 40 and 100 kV as a function of probe position (a) and (b) from an area approximately 2400 \AA thick and (c) from an area ~ 1.2 μm thick.



from Hutchings et. al.



#26

SI

Hutchings, et. al (1978)
Ultramicroscopy 3. 401.